

## References

- [1] Rao R. Tummala, *Fundamentals of Microsystems packaging*, International Edition 2001.
- [2] S. Chakraborty, K. Lim, A Sutono, E. Chen, S. Yoon, A. Obatoyinbo, S. –W. Yoon, M. Maeng, M. F. Davis, S. Pinel, and J. Laskar, “A 2.4-GHz Radio Front End in RF System-on-Package Technology”, *IEEE Microwave Magazine*, pp.94-104, 2002.
- [3] Kurman, B.K., Mita, S.G., “Gold-Gold (Au-Au) thermocompression (TC) bonding of very large arrays”, *Electronic Components and Technology Conference*, 1992. Proceedings., 42<sup>nd</sup> 18-20 May 1992 Page(s):883 – 889.
- [4] Break news from Eetimes (<http://www.eetimes.com>)
- [5] The product information of Philips Corp.
- [6] J. W. Lin, C. C. Chen, and Y. T. Cheng, “An Robust High Q Micromachined RF Inductor for RFIC Applications”, *IEEE Trans. on Elec. Dev.*, Vol. 52, pp. 1489- 1496, 2005.
- [7] H. M. Greenhouse, “Design of planar rectangular microelectronic inductor”, *IEEE trans. Parts, Hybrids, Packag.*, vol. PHP-10, pp.101-109, June 1974.
- [8] Jenei S., Nauwelaers, B.K.J.C., and Decoutere, S., “Physics-Based Closed-Form Inductance Expression for Compact Modeling of Integrated Spiral Inductors”, *Solid-State Circuits*, IEEE Journal of Volume 37, Issue 1, Jan. 2002.
- [9] Chia-Hsin Wu, “Analysis of on-chip spiral inductors using the distributed capacitance model”, *Solid-State Circuits*, IEEE Journal, 2003.
- [10] Yang-Chaun Chen, *Broadband Tunable Low Noise Amplifier for Ultra-Wideband*, Master Thesis, National Chiao-Tung University, 2005.
- [11] Yu Cao, Robert, A. Groves, X. Huang, N. D. Zamdmer, J. O. Plouchart, R. A. Wachnik, T.-J. King and C. Hu, ”Frequency-Independent Equivalent-Circuit Model for On-Chip Spiral Inductors”, *IEEE J. of solid-state Circuits*, vol. 38, no. 3, pp.419-426, March 2003.
- [12] C. Patrick Yue, S. Simon Wang, “On-Chip Spiral Inductors with Patterned Ground Shields for Si-Based RF IC’s”, *IEEE J. of solid-state Circuits*, vol. 33, no. 5, pp.743-752, May 1998.

- [13] Saman Asgaran, “New Accurate Physics-Based Closed-Form Expressions for Compact Modeling and Design of On-chip Spiral Inductors”, *IEEE Microelectronics*, pp.247-250, Dec 2002.
- [14] Grover, Frederick Warren, *Inductance Calculations: Working Formulas and Tables*, 1946, Van Nostrand Co.
- [15] A. Zolfaghari, A. Chan, and B. Razavi, “Stacked inductors and transformers in CMOS technology”, *IEEE J. Solid-State Circuits*, vol. 36, pp. 620-628, Apr. 2001.
- [16] Charles S. Walker, *Capacitance, Inductance, and Crosstalk Analysis*, published by Artech House, Boston. London.
- [17] C. P. Yue, C. Ryu, J. Lau, T. H. Lee, and S. S. Wong, “A Physical Model for Planar Spiral Inductors on Silicon”, in *IEEE IEDM Dig. Tech. Papers*, 1996, pp. 28-29.
- [18] Manual of Ansoft HFSS, *conf. NCHC*, R.O.C
- [19] David M. Pozar, *Microwave Engineering*, Third Edition, 2005.
- [20] Guang-Ren Shen, *Properties Enhancements of Ni-P-CNTs and Ni-P-Diamond Nanocomposites Films and the Applications on MEMS Device*, Master Thesis, National Chiao-Tung University, 2004.



## Vita and Publication

姓 名： 黃俊凱 (Jiun-Kai Huang)

學 歷：

國立台中第一高級中學 ( 1996.9. ~ 1999.6.)

(Tai-Chung First Senior High School)

國立清華大學原子科學系 ( 1999.9. ~ 2003.6.)

(Department of Nuclear Science, National Tsing Hua University)

國立交通大學電子工程所碩士班 ( 2003.9. ~ 2005.8.)

(Department of Electronics Engineering & Institute of Electronics,

National Chiao Tung University)



發表著作 (Publication)：

1. Jr-Wei Lin, C. C. Chen, J. K. Huang, and Y. T. Cheng, “An Optimum Design of The Micromachined RF Inductor”, *IEEE Radio Frequency Integrated Circuits Symposium*, pp.639-642, Fort Worth TX, 6-8 June 2004.